

PATENT ABSTRACTS OF JAPAN

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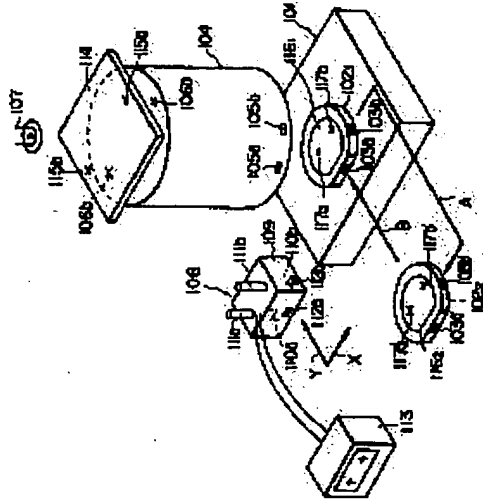
(54) METHOD FOR WAFER EXPOSURE AND DEVICE THEREOF

(57)Abstract:

PURPOSE: To contrive the improvement of through-put of the exposing operation for the subject wafer by a method wherein, when a step-and-repeat exposure is performed on the wafer, another wafer is operated simultaneously with the above wafer.

CONSTITUTION: A mask 114 having a prescribed pattern is matched to a cylinder 104, a positioning is performed on a wafer chuck 1021, wherein a wafer 1161 that was positioned in advance by positioning structure 108 was assembled, and the mirror cylinder 104 are positioned, and the wafer 1161 is matched to the mask 114. Then, a step-and-repeat is performed on the chuck 1021 for each stage 101 in X-Y direction, a plurality of patterns are repeatedly transferred on the wafer 1161. Thus, while the exposure is performed on the wafer 1161, the wafer 1162 is assembled in the wafer 1022, and

the positioning of the wafer 1162 is performed using the structure 108. Then, after the exposure has been finished, the chuck 1021 is moved in the direction shown by an arrow and positioned at a point below the structure 108, and at the same time, the chuck 1022 is placed on the stage 101, and a step-and-repeat exposure is performed on the wafer 1162 in the same manner as above.



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